

RH1028M/RH1128M
Ultralow Noise Precision
High Speed Op Amps
PAD FUNCTION

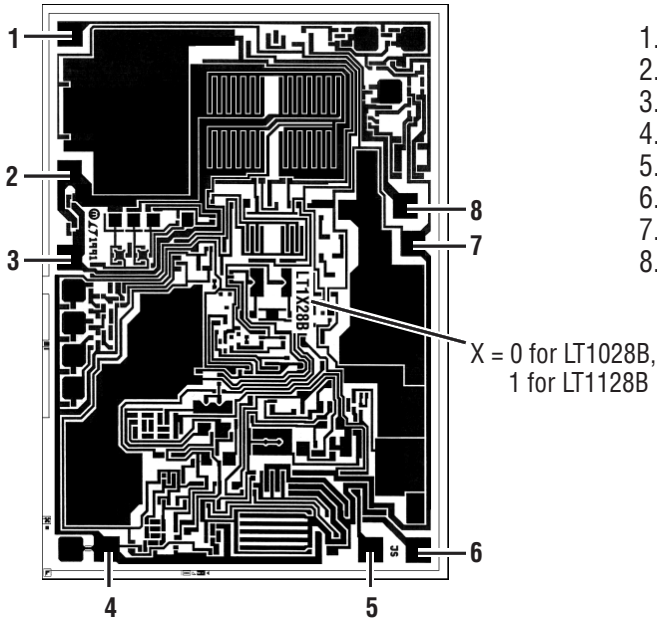
1. V_{OS} TRIM
2. $-IN$
3. $+IN$
4. V^-
5. OVER-COMP
6. OUT
7. V^+
8. V_{OS} TRIM

DIE CROSS REFERENCE


LTC Finished Part Number	Order Part Number
RH1028MW RH1028MW	RH1028 DICE RH1028 DWF*
RH1128MW RH1128MW	RH1128 DICE RH1128 DWF*

Please refer to LTC standard product data sheet for other applicable product information.

*DWF = DICE in wafer form.



114mils × 81mils,
 Backside (substrate) metal: Alloyed gold layer
 Backside potential: Connect to V^-

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DICE/DWF ELECTRICAL TEST LIMITS $V_S = \pm 15V$, $T_A = 25^\circ C$, $V_{CM} = 0V$, unless otherwise noted.

SYMBOL	PARAMETER	CONDITIONS	MIN	MAX	UNITS
V_{OS}	Input Offset Voltage (Note 1)			300	μV
I_{OS}	Input Offset Current	$V_{CM} = 0V$		150	nA
I_B	Input Bias Current	$V_{CM} = 0V$		± 400	nA
V_{IN}	Input Voltage Range		± 11		V
CMRR	Common Mode Rejection Ratio	$V_{CM} = \pm 11V$ $V_{CM} = \pm 10.3V$	110		dB
PSRR	Power Supply Rejection Ratio	$V_S = \pm 4V$ to $\pm 16V$ $V_S = \pm 4.5V$ to $\pm 16V$	110		dB
A_{VOL}	Large Scale Voltage Gain	$R_L \geq 2k$, $V_O = \pm 10V$ $R_L \geq 1k$, $V_O = \pm 10V$ $R_L \geq 600\Omega$, $V_O = \pm 10V$	5 3.5 2		$V/\mu V$ $V/\mu V$ $V/\mu V$
V_{OUT}	Maximum Output Voltage Swing	$R_L \geq 2k$ $R_L \geq 600\Omega$	± 12 ± 10.5		V V

DICE/DWF SPECIFICATION

RH1028M/RH1128M

DICE/DWF ELECTRICAL TEST LIMITS $V_S = \pm 15V$, $T_A = 25^\circ C$, $V_{CM} = 0V$, unless otherwise noted.

SYMBOL	PARAMETER	CONDITIONS	MIN	MAX	UNITS
SR	Slew Rate	$A_{VCL} = -1$ (RH1028)	11		V/ μ s
		$A_{VCL} = -1$ (RH1128)	4.5		V/ μ s
I_S	Supply Current			10.5	mA

Note 1: Input offset voltage measurements are performed by automatic test equipment approximately 0.5 seconds after application of power.

Wafer level testing is performed per the indicated specifications for dice. Considerable differences in performance can often be observed for dice versus packaged units due to the influences of packaging and assembly on certain devices and/or parameters. Please consult factory for more information on dice performance and lot qualifications via lot sampling test procedures.

Dice data sheet subject to change. Please consult factory for current revision in production.

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